

**Amendments to the Specification**

Please amend the title as follows.

Methods of Removing ~~at least some of a~~ Material from a Semiconductor Substrate

At page 1, prior to the technical field section, please insert the following new paragraph.

**RELATED PATENT DATA**

This patent resulted from a continuation of U.S. Patent Application Serial No. 09/653,157, filed on August 31, 2000.